MBRYONICS

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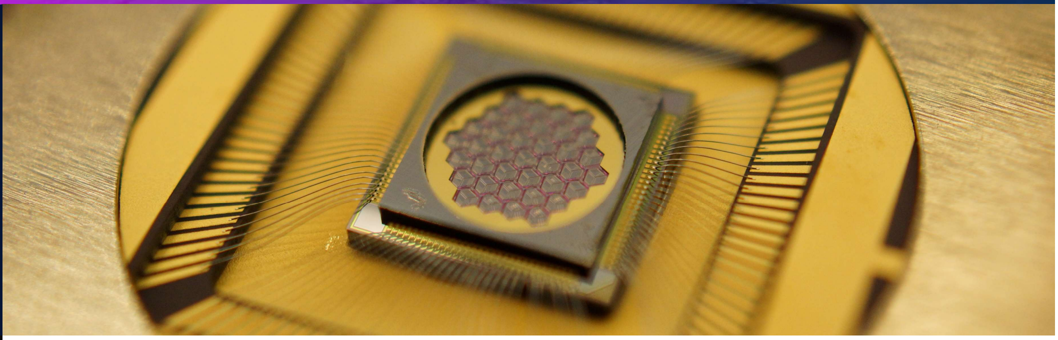
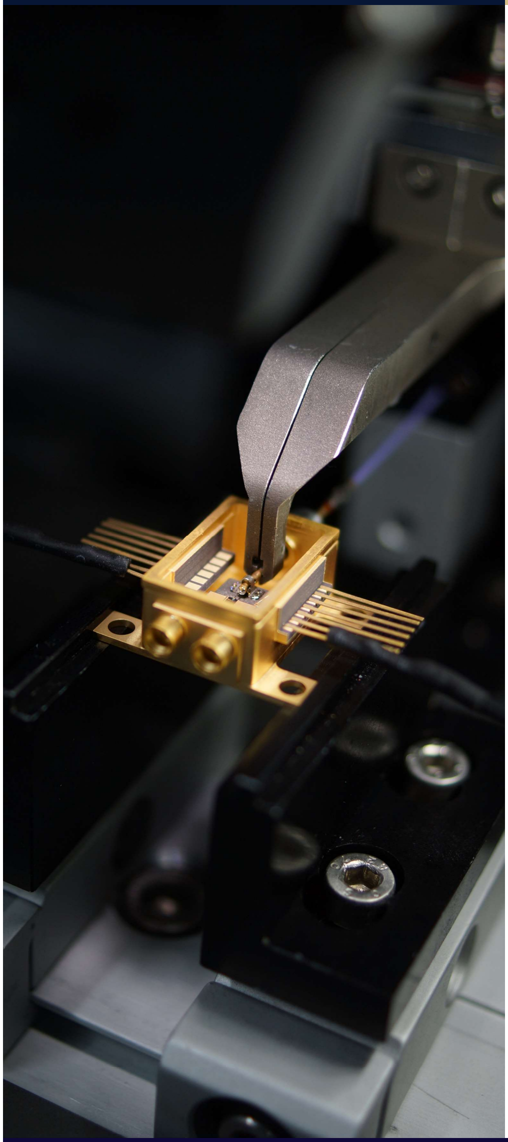
PakPIC

High-Precision Packaging Service

PAKPIC





PakPIC Services

- Fibre Array attach process
    - Lidded and lidless fibre arrays
    - 8, 12, 16 channel fibre arrays (32-channel by request)
    - 127 µm or 250 µm pitch
    - UHNA (3 µm SSCs) or SSMF (6-10 µm SSCs)
- Mechanical Mounting
    - Silver Epoxy or thermally conductive epoxy bond
    - Pick and place or manual, depending on complexity
- Flip-chip bonding (low volume)
    - <1 µm placement accuracy
    - Reflow up to 300 °C
- Mechanical package design and fabrication
- Foundry-agnostic packaging of SOI, SiN, and InP systems
- Packaging available in number of standard package formats
- High-precision wire bonding*

Design consultancy

- PIC design/layout for packaging (subject to design rules)
- Packaging feasibility study
- Bespoke mechanical packages
- Design for vacuum

Supply-chain support

- Fibre arrays
- Electronic components such as TECs, thermistors, etc.
- PCB manufacturing for low and high-speed applications

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*Coming soon: system awaiting qualification